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Applicant: *๛๛๛๛๛๛๛๛* Arjun Selvakumar et al. **US Application No.:** International Application No: PCT/US00/06832

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Title: Low Stress Die Attachment

a package;

Attorney Docket: IO-1015US

PRELIMINARY AMENDMENT

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With the transmission of the filing of the referenced application under 35 USC 3.71, Applicants submit the following Preliminary Amendment.

IN THE CLAIMS

Please delete the originally filed claims 1-2.

Please add the following new claims and proceed with the national examination procedures under 35 USC 3.71:

1. An apparatus including thermal stress reduction, comprising:

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including an active region; and 108 one or more substantially rigid members for attaching at least one point on the surface to the package to create a resilient coupling between the mass and the package, wherein at least a portion of the active region is spaced apart from the at least one point of attachment.

a mass coupled to the package, the mass having a surface, the mass further